

Description

The IRLR6225 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 20V I_{D} = 80 A$

 $R_{DS(ON)} < 5m\Omega$ @ V_{GS} =4.5V

Application

Battery protection

Load switch

Uninterruptible power supply



PIN3 S

N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IRLR6225	TO-252-2L(DPAK)	HXY MOSFET	2500

Absolute Maximum Ratings (T_c=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	20	V
V _G s	Gate-Source Voltage	±12	V
I _D	Drain Current-Continuous	80	Α
I _D (100℃)	Drain Current-Continuous(T _C =100 °C)	42	Α
Ірм	Pulsed Drain Current	210	Α
P _D	Maximum Power Dissipation	70	W
	Derating factor	0.48	W/℃
Eas	Single pulse avalanche energy	200	mJ
ТЈ,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}\!\mathbb{C}$
Rejc	Thermal Resistance,Junction-to-Case	2.1	°C/W

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics		•		,		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	<u> </u>	1	1			•
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	0.5	0.75	1.0	V
Dunin Course On State Besistance		V _{GS} =4.5V, I _D =20 A	-	3.5	5	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =15A		5.5	7	mΩ
Forward Transconductance	G FS	V _{DS} =10V,I _D =20A	15	-	-	S
Dynamic Characteristics (Note4)			-			
Input Capacitance	C _{lss}	\/ -40\/\/ -0\/	-	2000	-	PF
Output Capacitance	Coss	$V_{DS}=10V, V_{GS}=0V,$	-	500	-	PF
Reverse Transfer Capacitance	C_{rss}	F=1.0MHz	-	200	-	PF
Switching Characteristics (Note 4)	<u> </u>		<u>'</u>			
Turn-on Delay Time	t _{d(on)}		-	6.4	-	nS
Turn-on Rise Time	t _r	V_{DD} =10V, I_{D} =2A, R_{L} =1 Ω	-	17.2	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =4.5 V , R_{G} =3 Ω	-	29.6	-	nS
Turn-Off Fall Time	t _f		-	16.8	-	nS
Total Gate Charge	Qg	\/ 40\/ L 00A	-	27		nC
Gate-Source Charge	Q _{gs}	V _{DS} =10V,I _D =20A,	-	6.5		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	6.4		nC
Drain-Source Diode Characteristics		1	-1			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	80	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	25	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	24	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

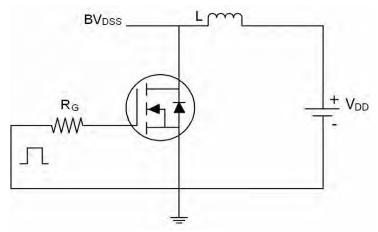
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E_{AS} condition : Tj=25 $^{\circ}\text{C}$,V_{DD}=10V,V_G=10V,L=0.5mH,Rg=25 Ω ,

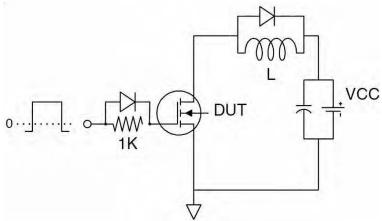


Test circuit

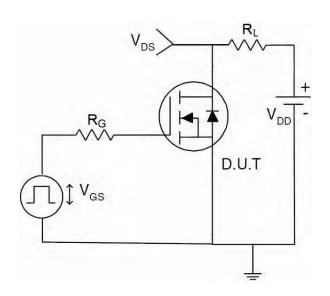
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

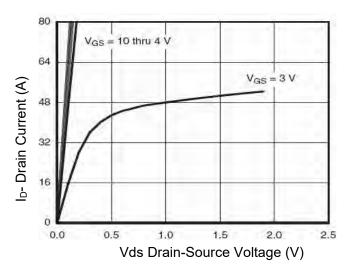


Fig.1 Typical Output Characteristics



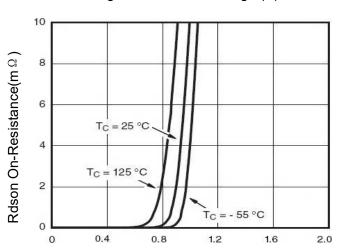


Figure 2 Transfer Characteristics

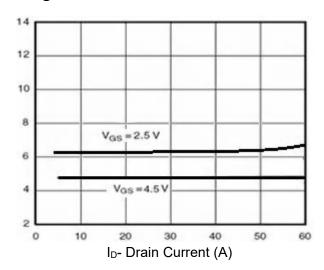


Figure 3 Rdson- Drain Current

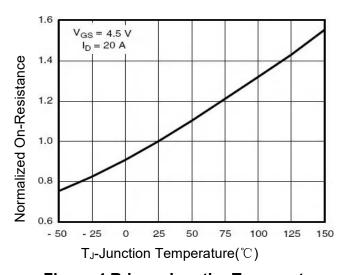


Figure 4 Rdson-JunctionTemperature

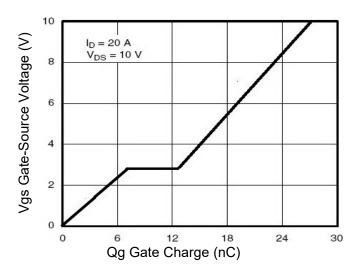


Figure 5 Gate Charge

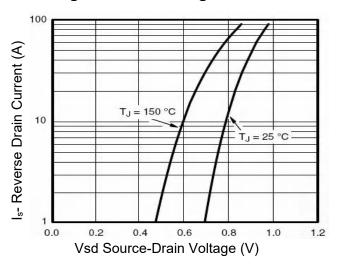


Figure 6 Source- Drain Diode Forward

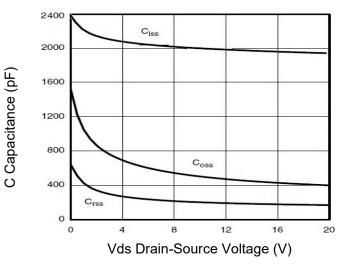


Figure 7 Capacitance vs Vds

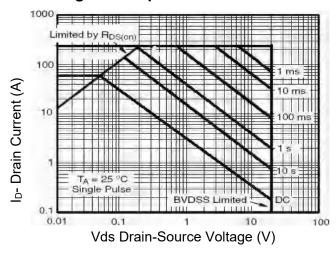


Figure 8 Safe Operation Area

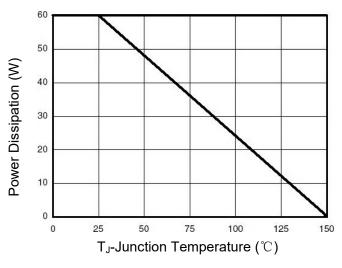


Figure 9 Power De-rating

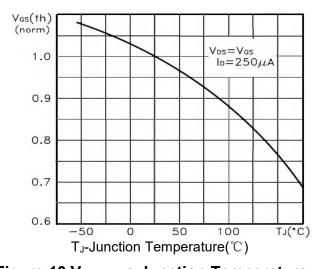
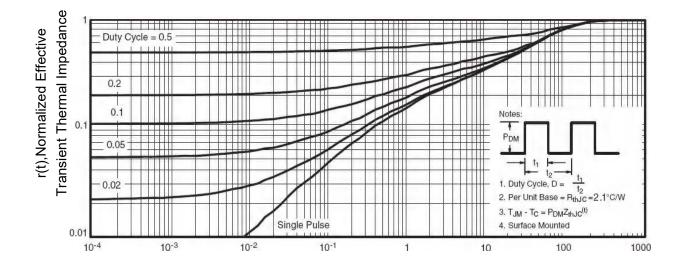


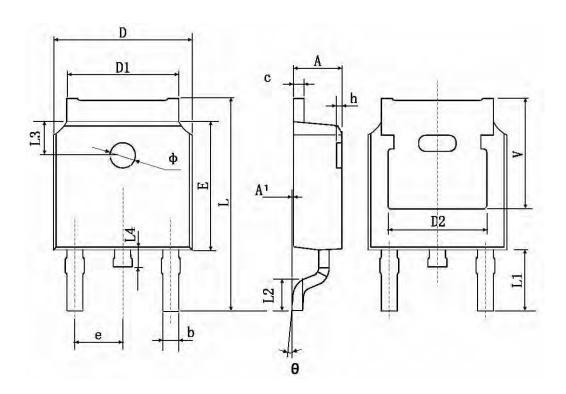
Figure 10 V_{GS(th)} vs Junction Temperature



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-2L(DPAK) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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